



## Material Content Data Sheet



<b>Sales Product Name</b>		SAF-XC888CM-8FFI 5V AC		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001127792						
<b>Package</b>		PG-LQFP-64-14		<b>Weight*</b>		373.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.934	3.19	3.19	31946	31946
leadframe	non noble metal	magnesium	7439-95-4	0.172	0.05		459	
	inorganic material	silicon	7440-21-3	0.743	0.20		1990	
	non noble metal	nickel	7440-02-0	3.431	0.92		9184	
wire	non noble metal	copper	7440-50-8	110.016	29.45	30.62	294490	306123
	noble metal	gold	7440-57-5	1.205	0.32	0.32	3224	3224
	encapsulation	organic material	carbon black	1333-86-4	1.188	0.32		3180
encapsulation	plastics	epoxy resin	-	32.076	8.59		85860	
	inorganic material	silicondioxide	60676-86-0	204.334	54.69	63.60	546961	636001
leadfinish	non noble metal	tin	7440-31-5	4.118	1.10	1.10	11022	11022
plating	noble metal	silver	7440-22-4	1.663	0.45	0.45	4452	4452
glue	plastics	epoxy resin	-	0.675	0.18		1808	
	noble metal	silver	7440-22-4	2.026	0.54	0.72	5424	7232
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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